

# SOT1034-1

plastic ball grid array package; 736 balls

8 February 2016

Package information

## 1. Package summary

<b>Terminal position code</b>	B (bottom)
<b>Package type descriptive code</b>	BGA736
<b>Package type industry code</b>	BGA736
<b>Package style descriptive code</b>	BGA (ball grid array)
<b>Package style suffix code</b>	NA (not applicable)
<b>Package body material type</b>	P (plastic)
<b>Mounting method type</b>	S (surface mount)
<b>Issue date</b>	28-9-2007

Table 1. Package summary

Symbol	Parameter	Min	Typ	Nom	Max	Unit
D	package length	34.8	-	35	35.2	mm
E	package width	34.8	-	35	35.2	mm
A	seated height	[tbd]	-	2.45	2.45	mm
A <sub>2</sub>	package height	1.6	-	1.85	1.85	mm
n <sub>2</sub>	actual quantity of termination	-	-	736	-	



## 2. Package outline

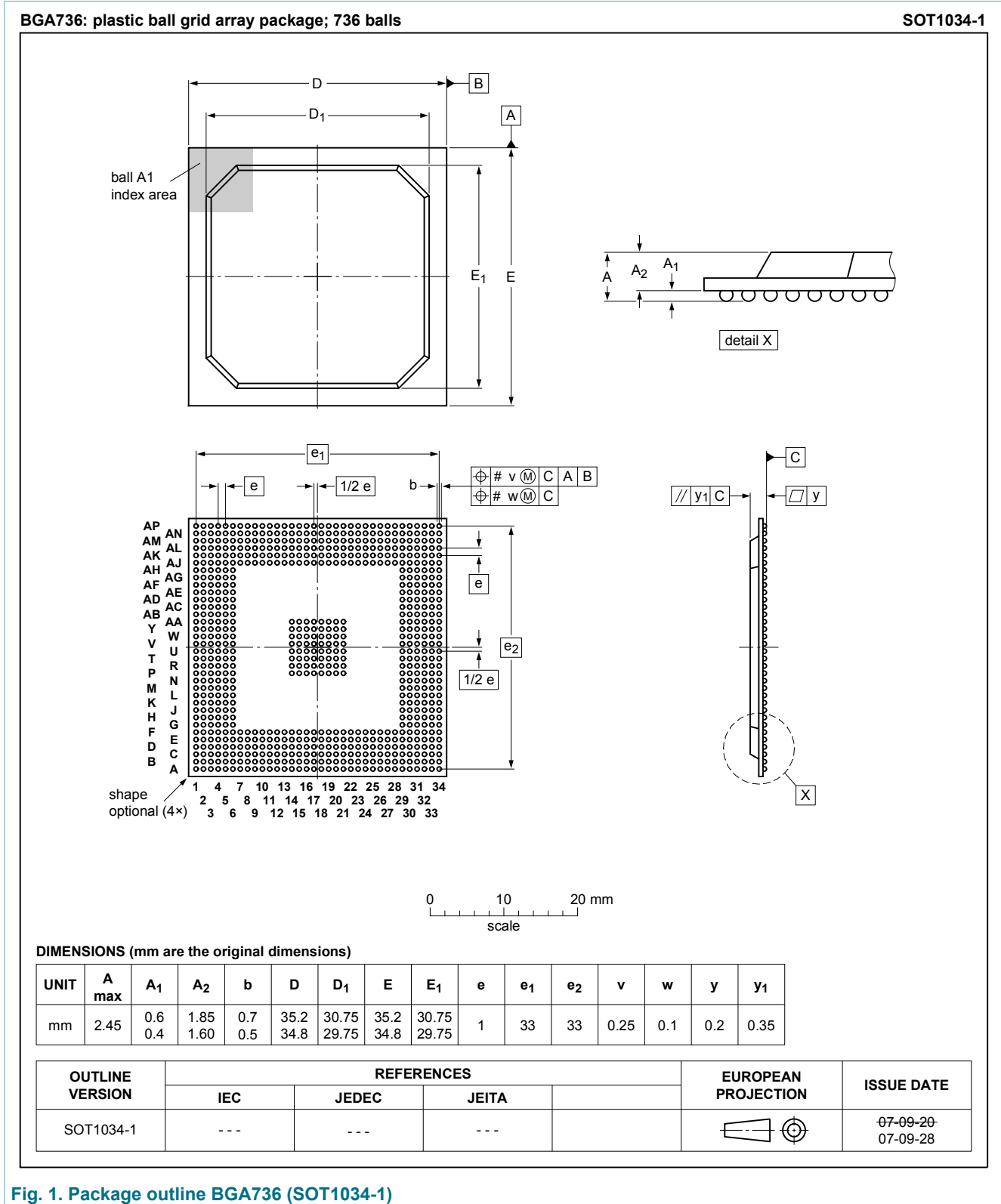


Fig. 1. Package outline BGA736 (SOT1034-1)

### 3. Legal information

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